



## KE-5540U

Shin-Etsu Silicones of America, Inc.  
800-544-1745

### Product Description

Shin-Etsu KE-5540 U is a nominal 40 durometer phenyl (PVMQ) base.

### Product Features

- This material was designed for its excellent vibration dampening characteristics. Because of its phenyl content, it also has excellent low temperature characteristics.

### Typical Applications

- Electronic CD mounts.
- Motor and engine mounts.
- Military and aeronautical vibration dampening devices.

### Typical Properties

	Low Temperature
Type of HCR	
Cure Agent	C-8
Durometer	42
Tensile Strength (psi)	1390
Elongation (%)	800
Specific Gravity	1.23
Tear Die B (ppi)	220
Compression Set (%)	13
Comp. Set Time (hours)	22
Comp. Set Temp. (°C)	180
Comp. Set Temp. (°F)	356
Press Cure/Post Cure	Press
Cure Time (minutes)	165
Cure Temp. (°C)	10
Cure Temp. (°F)	50
Post Cure Time (hours)	4
Post Cure Temp. (°C)	200
Post Cure Temp. (°F)	392

*Note: Values are not for specification purposes.*

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